




## Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-03-11
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C01-RMN6TP	PX07*24011TA	A	9998	2017-03-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	JEDEC	8	Gull Wing	
Comment	Package : 07 SO 08 .15 JEDEC 0016023			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PX07*24011TA				6000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.238	mg	supplier	die	Silicon (Si)	7440-21-3		0.229	mg	962185	2863
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	4202	13
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	4202	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	29412	88
LEADFRAME	M-011 Other inorganic materials	51.527	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		49.798	mg	966445	622475
				supplier	ALLOY	Iron (Fe)	7439-89-6		1.200	mg	23289	15000
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.062	mg	1203	775
				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.015	mg	291	188
				supplier	COATING	Nickel (Ni)	7440-02-0		0.439	mg	8520	5488
				supplier	COATING	Palladium (Pd)	7440-05-3		0.009	mg	175	113
				supplier	COATING	Gold (Au)	7440-57-5		0.004	mg	78	50
DIE ATTACH	M-011 Other inorganic materials	0.173	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.012	mg	69364	150
				supplier	GLUE	Epoxy resin B	68475-94-5		0.007	mg	40462	88
				supplier	GLUE	Silver(Ag)	7440-22-4		0.133	mg	768786	1663
				supplier	GLUE	Lactone	96-48-0		0.007	mg	40462	88
				supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.007	mg	40462	88
supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0.007	mg	40462	88				
BONDING WIRE	M-011 Other inorganic materials	0.099	mg	supplier	BONDING WIRE	Copper (Cu)	7440-50-8		0.097	mg	979798	1213
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.002	mg	20202	25
ENCAPSULATION	M-011 Other inorganic materials	27.773	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		3.198	mg	115148	39975
				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		24.436	mg	879847	305450
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.139	mg	5005	1738
FINISHING	M-011 Other inorganic materials	0.190	mg	supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		0.185	mg	973684	2313
				supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0.004	mg	21053	50
				supplier	CONNECTION COATING	Gold (Au)	7440-57-5		0.001	mg	5263	13